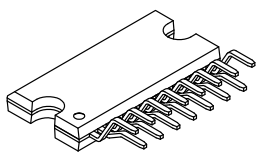


MECHANICAL CASE OUTLINE

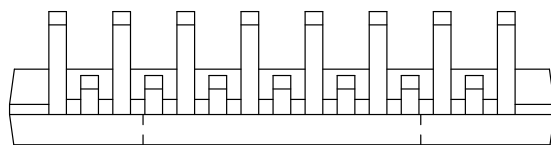
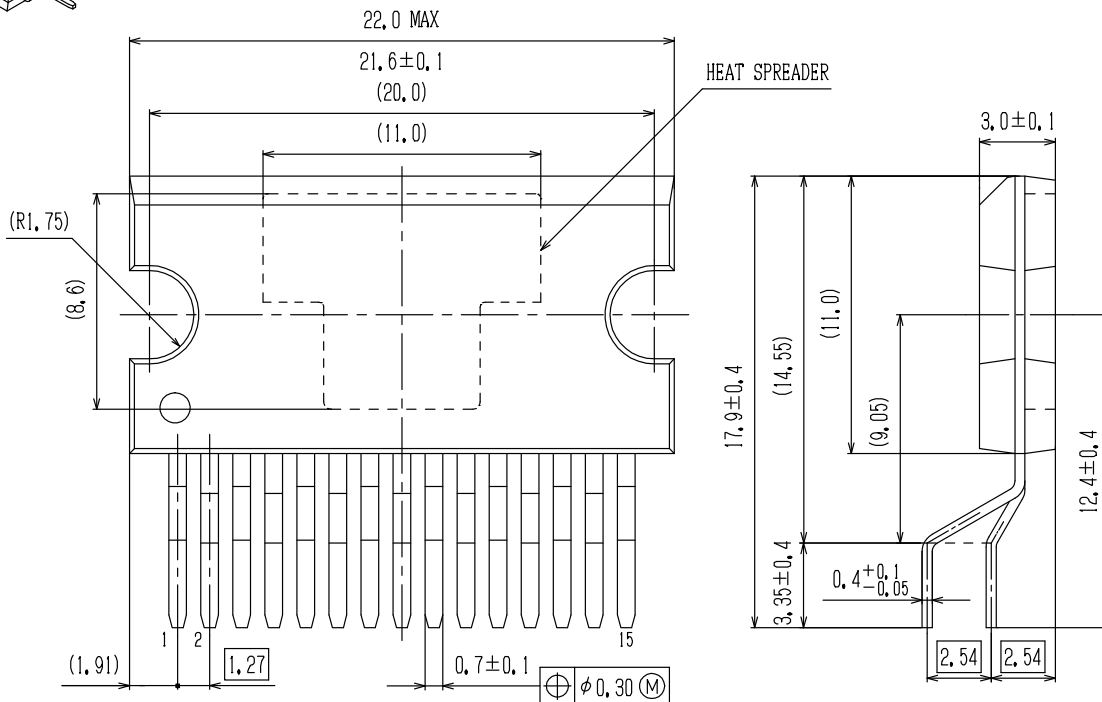
PACKAGE DIMENSIONS

ON Semiconductor®



HZIP15
CASE 945AB
ISSUE A

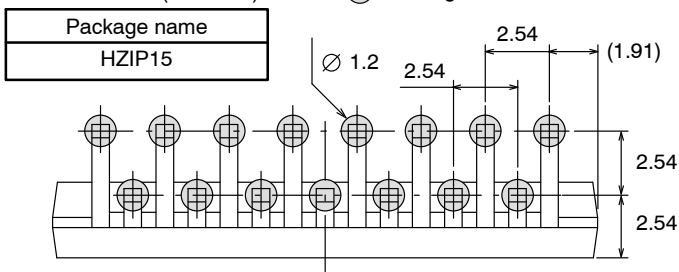
DATE 24 OCT 2013



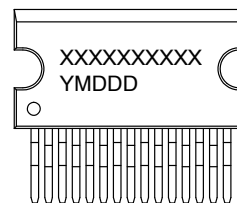
SOLDERING FOOTPRINT*

(Unit: mm)

○ Through Hole Area



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

Y = Year

M = Month

DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| NEW STANDARD: | | |
| DESCRIPTION: | HZIP15 | PAGE 1 OF 2 |

